EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	416891	reactor	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2007/07/25 10:40
L2	18327	manhole	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2007/07/25 10:42
L3	369038	partition	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2007/07/25 10:40
L4	262	L2 same L3	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2007/07/25 10:40
L5	23	manhole adj nozzle	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2007/07/25 10:40
L6	74	L2 near5 L3	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2007/07/25 10:40
L7	5	L1 near5 L6	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2007/07/25 10:40
L8	88884	("422").CLAS.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2007/07/25 10:40
L9	182	L2 and L8	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2007/07/25 10:40
L10	38	L3 and L9	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2007/07/25 10:40
L11	3	L6 and L8	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2007/07/25 10:40

EAST Search History

L12	8199	sampling near5 tube	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2007/07/25 10:40
L13	3	L12 and L6	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2007/07/25 10:40
L14	1	"9859990"	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2007/07/25 10:40
L15	877265	catalyst	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2007/07/25 10:40
L16	14374	L3 and L15	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2007/07/25 10:40
L17	41	L12 and L16	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2007/07/25 10:40
L18	3	("5747708").URPN.	USPAT	OR	ON	2007/07/25 10:40
L19	3	"9958950"	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2007/07/25 10:40
L20	186673	jacket$	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2007/07/25 10:40
L21	95	L12 same L20	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2007/07/25 10:40
L22	29	L12 near10 L20	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2007/07/25 10:40
L23	1	53-94940	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2007/07/25 10:40
L24	0	53-094940	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2007/07/25 10:40

EAST Search History

L25	2	"5394940"	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2007/07/25 10:40
L26	853018	window	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2007/07/25 10:40
L27	118	L2 same L26	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2007/07/25 10:40
L28	2762894	gas	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2007/07/25 10:40
L29	700	422/119.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2007/07/25 11:06
L30	2	L2 and L29	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2007/07/25 10:40
L31	653252	oxidat$	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2007/07/25 10:40
L32	8	L27 same L28	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2007/07/25 10:40
L33	3	"53094940"	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2007/07/25 10:40
L34	53	L29 and L31	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2007/07/25 10:40
L35	8	L20 and L34	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2007/07/25 10:40
L36	65635	relief near10 valve	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2007/07/25 10:43

EAST Search History

L37	104	l2 same l36	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2007/07/25 10:46
L38	2	l1 same l37	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2007/07/25 10:44
L39	263707	stopper	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2007/07/25 11:10
L40	7	l37 and l39	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2007/07/25 10:53
L41	5775	gas near10 curtain	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2007/07/25 10:54
L42	0	l37 and l41	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2007/07/25 10:54
L43	13	l29 and l36	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2007/07/25 10:57
L44	465745	acrylic	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2007/07/25 11:07
L45	22	l29 and l44	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2007/07/25 11:07
L46	5	l39 same l41	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2007/07/25 11:54
L47	2	("6655664").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2007/07/25 12:05
L48	4	(stopper and manhole and plate).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2007/07/25 12:09

EAST Search History

L49	221	(stopper and nozzle and plate).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2007/07/25 12:17
L50	10	l8 and l49	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2007/07/25 12:17

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NEWS 6	MAR 30	RDISCLOSURE reloaded with enhancements
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NEWS 12	MAY 01	New CAS web site launched
NEWS 13	MAY 08	CA/CAplus Indian patent publication number format defined
NEWS 14	MAY 14	RDISCLOSURE on STN Easy enhanced with new search and display fields
NEWS 15	MAY 21	BIOSIS reloaded and enhanced with archival data
NEWS 16	MAY 21	TOXCENTER enhanced with BIOSIS reload
NEWS 17	MAY 21	CA/CAplus enhanced with additional kind codes for German patents
NEWS 18	MAY 22	CA/CAplus enhanced with IPC reclassification in Japanese patents
NEWS 19	JUN 27	CA/CAplus enhanced with pre-1967 CAS Registry Numbers
NEWS 20	JUN 29	STN Viewer now available
NEWS 21	JUN 29	STN Express, Version 8.2, now available
NEWS 22	JUL 02	LEMBASE coverage updated
NEWS 23	JUL 02	LMEDLINE coverage updated
NEWS 24	JUL 02	SCISEARCH enhanced with complete author names
NEWS 25	JUL 02	CHEMCATS accession numbers revised
NEWS 26	JUL 02	CA/CAplus enhanced with utility model patents from China
NEWS 27	JUL 16	CAplus enhanced with French and German abstracts
NEWS 28	JUL 18	CA/CAplus patent coverage enhanced

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CURRENT MACINTOSH VERSION IS V6.0c(ENG) AND V6.0Jc(JP),
AND CURRENT DISCOVER FILE IS DATED 05 JULY 2007.

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FILE LAST UPDATED: 24 Jul 2007  (20070724/ED)

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=> relief valve
         32797 RELIEF
           860 RELIEFS
         33211 RELIEF
                 (RELIEF OR RELIEFS)
         80724 VALVE
         39498 VALVES
         99839 VALVE
                 (VALVE OR VALVES)
L1        1489 RELIEF VALVE
                 (RELIEF(W)VALVE)

=> gas curtain
       1597592 GAS
        530797 GASES
       1783967 GAS
                 (GAS OR GASES)
          4104 CURTAIN
          1510 CURTAINS
          4899 CURTAIN
                 (CURTAIN OR CURTAINS)
L2         185 GAS CURTAIN
                 (GAS(W)CURTAIN)

=> l1 and l2
L3           0 L1 AND L2

=> stopper
         12224 STOPPER
          3445 STOPPERS
L4       14276 STOPPER
                 (STOPPER OR STOPPERS)

=> l1 and l4
L5           9 L1 AND L4
```

```
=> d l5 1-9 ti

L5   ANSWER 1 OF 9  CAPLUS  COPYRIGHT 2007 ACS on STN
TI   Apparatus for sampling of well liquids

L5   ANSWER 2 OF 9  CAPLUS  COPYRIGHT 2007 ACS on STN
TI   Device and method for removing bad smell from food waste collection
     container which is furnished in apartment complex and restaurant, etc

L5   ANSWER 3 OF 9  CAPLUS  COPYRIGHT 2007 ACS on STN
TI   Adjustable bubble generator practical for use as a relief
     valve

L5   ANSWER 4 OF 9  CAPLUS  COPYRIGHT 2007 ACS on STN
TI   Relief valve for filtration equipment for clarifying.
     [Machine Translation].

L5   ANSWER 5 OF 9  CAPLUS  COPYRIGHT 2007 ACS on STN
TI   Excess pressure valve and alkaline battery fitted with it

L5   ANSWER 6 OF 9  CAPLUS  COPYRIGHT 2007 ACS on STN
TI   Alterations of in vitro rumen fermentation patterns with various levels of
     sucrose and cellulose

L5   ANSWER 7 OF 9  CAPLUS  COPYRIGHT 2007 ACS on STN
TI   Relief valve for hazardous vacuum distillations

L5   ANSWER 8 OF 9  CAPLUS  COPYRIGHT 2007 ACS on STN
TI   Stoppers for carboys

L5   ANSWER 9 OF 9  CAPLUS  COPYRIGHT 2007 ACS on STN
TI   Automatic alarm for use in gas absorption


=> d l5 7 ti fbib abs

L5   ANSWER 7 OF 9  CAPLUS  COPYRIGHT 2007 ACS on STN
TI   Relief valve for hazardous vacuum distillations
AN   1949:15  CAPLUS <<LOGINID::20070725>>
DN   43:15
OREF 43:1h-i
TI   Relief valve for hazardous vacuum distillations
AU   Moore, Ralph G. D.
SO   Chemist-Analyst (1948), 37, 66
     CODEN: CHANAA; ISSN: 0095-8484
DT   Journal
LA   Unavailable
AB   With a 3-neck standard taper flask, one neck contains the safety valve
     which consists of an ordinary, standard taper joint cut off square about
     10 cm. above the joint and ground smooth.  On this is placed a 5-mm. disk
     of thick smooth rubber (perhaps cut from the bottom of a large rubber
     stopper) lubricated lightly with stopcock grease.  Under suction,
     this stays in place but it falls off when the pressure is a little more
     than that of the atmospheric


=> d l5 3 ti fbib abs

L5   ANSWER 3 OF 9  CAPLUS  COPYRIGHT 2007 ACS on STN
TI   Adjustable bubble generator practical for use as a relief
     valve
AN   2003:848997  CAPLUS <<LOGINID::20070725>>
TI   Adjustable bubble generator practical for use as a relief
```

valve
IN Chuang, Shuo Wei
PA Taiwan
SO U.S. Pat. Appl. Publ.
CODEN: USXXCO
DT Patent
LA English
FAN.CNT 1

	PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
PI	US 2003201552	A1	20031030	US 2002-134384	20020430
	US 6655664	B2	20031202		
				US 2002-134384	20020430

AB A bubble generator is constructed to include a cylindrical casing, a tapered tube suspended in a front open side of the casing and adapted for guiding water into the casing, the tapered tube having recessed holes on the inside adapted for causing a negative pressure when water passing through the tapered tube into the inside of the casing toward the water outlet, a rod member axially slidably inserted through a rear close side of the casing into the inside of the tapered tube, and a stopper fixedly fastened to the rod member and moved with the rod member to adjust the gap between the stopper and the tapered tube.

```
=> sampling valve
        132439 SAMPLING
          2024 SAMPLINGS
        133795 SAMPLING
                 (SAMPLING OR SAMPLINGS)
         80724 VALVE
         39498 VALVES
         99839 VALVE
                 (VALVE OR VALVES)
L6         477 SAMPLING VALVE
                 (SAMPLING(W)VALVE)

=> l2 and l6
L7           0 L2 AND L6

=> valve
         80724 VALVE
         39498 VALVES
L8       99839 VALVE
                 (VALVE OR VALVES)

=> d his

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     FILE 'CAPLUS' ENTERED AT 11:50:19 ON 25 JUL 2007
L1          1489 RELIEF VALVE
L2           185 GAS CURTAIN
L3             0 L1 AND L2
L4         14276 STOPPER
L5             9 L1 AND L4
L6           477 SAMPLING VALVE
L7             0 L2 AND L6
L8         99839 VALVE

=> l2 and l8
L9             4 L2 AND L8

=> d l9 1-4 ti fbib abs
```

L9 ANSWER 1 OF 4 CAPLUS COPYRIGHT 2007 ACS on STN
TI Substrate processing platform allowing processing in different ambients
AN 2006:1121233 CAPLUS <<LOGINID::20070725>>
TI Substrate processing platform allowing processing in different ambients
IN Yokota, Yoshitaka; Moritz, Kirk; Ma, Kai; Chang, Wen; Parasiris, Anastasios; Sharma, Rohit; Tjandra, Agus; Achutharaman, Vedapuram; Ramamurthy, Sundar; Thakur, Randhir
PA Applied Materials, Inc., USA
SO U.S. Pat. Appl. Publ.
CODEN: USXXCO
DT Patent
LA English
FAN.CNT 1

PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
PI US 2006240680	A1	20061026	US 2005-114250	20050425
WO 2006115857	A2	20061102	WO 2006-US14226	20060414
WO 2006115857	A3	20070308		

W: AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BW, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KM, KN, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, LY, MA, MD, MG, MK, MN, MW, MX, MZ, NA, NG, NI, NO, NZ, OM, PG, PH, PL, PT, RO, RU, SC, SD, SE, SG, SK, SL, SM, SY, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, YU, ZA, ZM, ZW
RW: AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HU, IE, IS, IT, LT, LU, LV, MC, NL, PL, PT, RO, SE, SI, SK, TR, BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG, BW, GH, GM, KE, LS, MW, MZ, NA, SD, SL, SZ, TZ, UG, ZM, ZW, AM, AZ, BY, KG, KZ, MD, RU, TJ, TM

US 2005-114250 A 20050425

AB A semiconductor wafer processing system including a factory interface operating at atmospheric pressure and mounting plural wafer cassettes and plural wafer processing chambers connected to the factory interface through respective slit valves. A robot in the factory interface can transfer wafers between the cassettes and the processing chambers. At least one of the processing chambers can operate at reduced pressure The processing chamber may be a rapid thermal processing chamber including an array of lamps irradiating a processing volume through a window. The lamphead is vacuum pumped to a pressure approximating that in the processing volume. A multi-step process may be performed with different pressures. The invention also includes a wafer access port of a thermal processing chamber which can flow an inert gas in outside of the slit valve to thereby form a gas curtain outside of the opened slit to prevent the out flow of toxic processing gases.

L9 ANSWER 2 OF 4 CAPLUS COPYRIGHT 2007 ACS on STN
TI Exposure apparatus, coating/developing apparatus, method of transferring a substrate, method of producing a device, semiconductor production factory, and method of maintaining an exposure apparatus
AN 2001:885568 CAPLUS <<LOGINID::20070725>>
DN 136:13003
TI Exposure apparatus, coating/developing apparatus, method of transferring a substrate, method of producing a device, semiconductor production factory, and method of maintaining an exposure apparatus
IN Deguchi, Nobuyoshi
PA Canon K. K., Japan
SO Eur. Pat. Appl., 27 pp.
CODEN: EPXXDW
DT Patent
LA English
FAN.CNT 1

PATENT NO.	KIND	DATE	APPLICATION NO.	DATE

PI	EP 1160839	A2	20011205	EP 2001-304750	20010530
	EP 1160839	A3	20040714		
	R: AT, BE, CH, DE, DK, ES, FR, GB, GR, IT, LI, LU, NL, SE, MC, PT, IE, SI, LT, LV, FI, RO				
				JP 2000-165026 A	20000601
	JP 2001345255	A	20011214	JP 2000-165026	20000601
	JP 3595756	B2	20041202		
	US 2002009813	A1	20020124	US 2001-864256	20010525
	US 6638672	B2	20031028		
				JP 2000-165026 A	20000601

AB Apparatus, especially exposure and resist coating/developing apparatus, which includes an enclosure having a controllable internal ambient, a gate valve through which a substrate is transferred into or out of the enclosure, and a gas ejection unit for ejecting a gas into a region in close proximity to the gate valve, and in a direction substantially perpendicular to the direction of movement of the substrate as it is transferred into or out of the enclosure is described in which a gas curtain is formed by the gas ejected by the gas ejection unit, so that an opening of the gate valve is shielded by the gas curtain, thereby suppressing intrusion or leakage of an ambient gas which can occur when the substrate is transferred into or out of the apparatus Methods of maintaining the apparatus are also described which entail allowing access to a maintenance database. Methods of transferring reticles and wafers into and out of the apparatus are also described, as are semiconductor device fabrication methods and factories.

L9 ANSWER 3 OF 4 CAPLUS COPYRIGHT 2007 ACS on STN
TI Semiconductor processing system and method using a gas curtain
AN 1997:354039 CAPLUS <<LOGINID::20070725>>
DN 126:337675
TI Semiconductor processing system and method using a gas curtain
IN Goodwin, Dennis L.; Hawkins, Mark R.; Crabb, Richard; Doley, Allan D.
PA Advanced Semiconductor Materials America, Inc., USA
SO PCT Int. Appl., 39 pp.
CODEN: PIXXD2
DT Patent
LA English
FAN.CNT 1

	PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
PI	WO 9714179	A1	19970417	WO 1996-US16346	19961014
	W: AL, AM, AT, AU, AZ, BA, BB, BG, BR, BY, CA, CH, CN, CU, CZ, DE, DK, EE, ES, FI, GB, GE, HU, IL, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MD, MG, MK, MN, MW, MX, NO, NZ, PL, PT, RO, RU, SD, SE, SG, SI, SK, TJ, TM, TR, TT, UA, UG, UZ, VN				
	RW: KE, LS, MW, SD, SZ, UG, AT, BE, CH, DE, DK, ES, FI, FR, GB, GR, IE, IT, LU, MC, NL, PT, SE, BF, BJ, CF, CG, CI				
				US 1995-5413P P	19951013
				US 1996-729550 A	19961011
	AU 9674415	A	19970430	AU 1996-74415	19961014
				US 1995-5413P P	19951013
				US 1996-729550 A	19961011
				WO 1996-US16346 W	19961014

AB A gas curtain for use with a semiconductor processing system to prevent unwanted gases from entering a processing chamber includes both upward and downward flows of gas surrounding an isolation valve adjacent to a delivery port into the processing chamber. In the valve open position, the downward flow extends between the valve and the delivery port, and the upward flow extends in the opposite direction behind the isolation valve. In the

valve closed position, 1 of the flows extends through a slot in the isolation valve, while the overflow is directed in the opposite direction on the rear side of the isolation valve. In a method of using the gas curtain apparatus, a pick-up wand operating on the Bernoulli principle uses gases which are unwanted in the processing chamber, and just prior to loading wafers into the processing chamber, the gas flow in the Bernoulli wand is switched from a 1st gas to a 2nd gas, preferably H. The Bernoulli wand passes through the gas curtain before entering the processing chamber to remove any fugitive particles, moisture, and unwanted gases. An exhaust located near an input/output chamber creates a continuous pressure gradient in the handling chamber toward the input/output chamber, further helping to prevent unwanted gases from entering the processing chamber.

L9 ANSWER 4 OF 4 CAPLUS COPYRIGHT 2007 ACS on STN
TI Pug mill for mixing water with recovered dust from blast-furnace waste gases
AN 1997:140041 CAPLUS <<LOGINID::20070725>>
DN 126:145690
TI Pug mill for mixing water with recovered dust from blast-furnace waste gases
IN Iwano, Takenori
PA Azuma Tekko Kk, Japan
SO Jpn. Kokai Tokkyo Koho, 4 pp.
CODEN: JKXXAF
DT Patent
LA Japanese
FAN.CNT 1

	PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
PI	JP 08320114	A	19961203	JP 1995-126336	19950525
				JP 1995-126336	19950525

AB The title apparatus includes gas-jet means arranged on its dust inlet for jetting an inert gas (e.g., N) to form a gas curtain for preventing leakage of water vapor. Gas-seal valve failure is avoided.

=> logoff hold

COST IN U.S. DOLLARS	SINCE FILE ENTRY	TOTAL SESSION
FULL ESTIMATED COST	47.87	48.29

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CA SUBSCRIBER PRICE	-4.68	-4.68

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